

#### **ABSOLUTE MAXIMUM RATINGS**

at.	$T_A$	=	25°	$\sim$
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Logic Supply Voltage, V <sub>DD</sub>	15	٧	
Driver Supply Voltage, V <sub>BB</sub>	60	V	
Continuous Output Current Range,			

I<sub>OUT</sub>..... -40 mA to +15 mA Input Voltage Range,

 $V_{IN}$  ...... -0.3 V to  $V_{DD}$  + 0.3 V Package Power Dissipation, Pp.

(UCN5810AF)................. 2.08 W\* (UCN5810EPF) ...... 1.60 W\* (UCN5810LWF) ..... 1.33 W\*

Operating Temperature Range,

T<sub>A</sub> .....-20°C to +85°C Storage Temperature Range,

T<sub>S</sub> ......-55°C to +150°C

\*Derate linearly to 0 W at +150°C.

Caution: CMOS devices have input static protection but are susceptible to damage when exposed to extremely high static electrical charges.

Note that the UCN5810AF (dual in-line package) and UCN5810LWF (small-outline IC package) are electrically identical and share a common terminal number assignment.

The UCN5810AF, UCN5810EPF, and UCN5810LWF combine a 10-bit CMOS shift register and accompanying data latches, control circuitry, bipolar sourcing outputs with DMOS active pull-downs. Designed primarily to drive vacuum-fluorescent displays, the 60 V and -40 mA output ratings also allow these devices to be used in many other peripheral power driver applications. The UCN5810AF/EPF/LWF feature reduced supply requirements (active DMOS pull-downs) and lower saturation voltages when compared with the original UCN5810A.

The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. With a 5 V supply, they will operate to at least 3.3 MHz. At 12 V, higher speeds are possible. Use with TTL may require appropriate pull-up resistors to ensure an input logic high.

A CMOS serial data output enables cascade connections in applications requiring additional drive lines. Similar devices are available as the UCN5811A (12 bits), UCN5812AF/EPF (20 bits), and UCN5818AF/EPF (32 bits).

The UCN5810AF/EPF/LWF output source drivers are NPN Darlingtons capable of sourcing up to 40 mA. The DMOS active pull-downs are capable of sinking up to 15 mA. For inter-digit blanking, all of the output drivers can be disabled and the DMOS sink drivers turned on by the BLANKING input high.

The UCN5810AF is furnished in an 18-pin dual in-line plastic package. The UCN5810EPF is furnished in a 20-lead plastic chip carrier. The UCN5810LWF is furnished in a wide-body, small-outline plastic package (SOIC) with gull-wing leads. Copper lead frames, reduced supply current requirements, and lower output saturation voltages allow all devices to source 25 mA from all outputs continuously, over the entire operating temperature range. All devices are also available for operation between -40°C and +85°C. To order, change the prefix from 'UCN' to 'UCQ'.

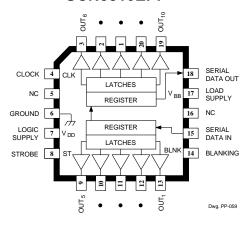
#### **FEATURES**

- 60 V Minimum Output Breakdown
- Improved Replacements for TL4810B
- High-Speed Source Drivers
  Low Output Saturation Voltages
  - Low-Power CMOS Logic and Latches
  - To 3.3 MHz Data Input Rate
  - Active DMOS Pull-Downs

Always order by complete part number, e.g., UCN5810AF



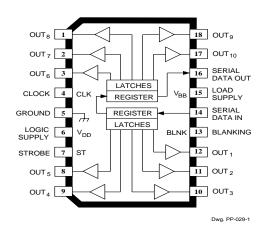
#### UCN5810EPF



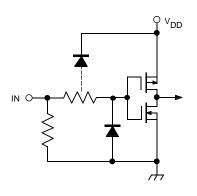
#### LOGIC SUPPLY V<sub>DD</sub>**∢**O CLOCK O SERIAL SERIAL DATA OUT SERIAL-PARALLEL SHIFT REGISTER DATA IN LATCHES STROBE C BLANKING MOS BIPOLAR LOAD OUT 1 OUT 2 OUT 3 GROUND OUT<sub>N</sub> Dwg. FP-013-1

**FUNCTIONAL BLOCK DIAGRAM** 

#### UCN5810LWF



#### TYPICAL INPUT CIRCUIT



Dwg. EP-010-4A

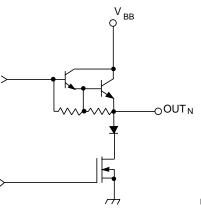
# ALLOWABLE PACKAGE POWER DISSIPATION IN WATTS SUFFIX 'A', ReJA = 60°C/W SUFFIX 'EP', ReJA = 78°C/W 1.5

2.0

25

## SUFFIX 'LW', Rela = 94°C/W 75 100 AMBIENT TEMPERATURE IN °C

#### **TYPICAL OUTPUT DRIVER**



Dwg. No. A-14,219



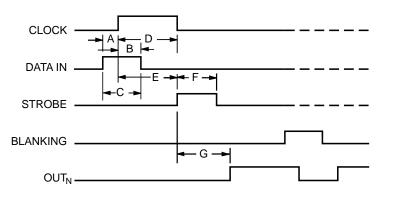
Dwg. GP-024C

## ELECTRICAL CHARACTERISTICS at $T_A$ = +25°C, $V_{BB}$ = 60 V unless otherwise noted.

			Limits @ V <sub>DD</sub> = 5 V			Limits			
Characteristic	Symbol	Test Conditions	MIn.	Тур.	Max.	Min.	Тур.	Max.	Units
Output Leakage Current	I <sub>CEX</sub>	V <sub>OUT</sub> = 0 V, T <sub>A</sub> = +70°C		-5.0	-15	_	-5.0	-15	μΑ
Output Voltage	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -25 mA	58	58.5	_	58	58.5	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 1 mA	_	1.0	1.5	_	_	_	V
		I <sub>OUT</sub> = 2 mA	_	_	_	_	1.0	1.5	V
Output Pull-Down Current	I <sub>OUT(0)</sub>	$V_{OUT} = 5 \text{ V to } V_{BB}$	2.0	3.5	_	_	_	_	mA
		V <sub>OUT</sub> = 20 V to V <sub>BB</sub>	_	_	_	8.0	13	_	mA
Input Voltage	V <sub>IN(1)</sub>		3.5	_	5.3	10.5	_	12.3	V
	V <sub>IN(0)</sub>		-0.3	_	+0.8	-0.3	_	+0.8	V
Input Current	I <sub>IN(1)</sub>	$V_{IN} = V_{DD}$	_	_	100	_	_	240	μΑ
	I <sub>IN(0)</sub>	V <sub>IN</sub> = 0.8 V	_	-0.05	-0.5	_	-0.1	-1.0	μΑ
Serial Data Output Voltage	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -200 μA	4.5	4.7	_	11.7	11.8	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 200 μA	_	200	250	_	100	200	mV
Maximum Clock Frequency	f <sub>clk</sub>		3.3*	_	_	_	_	_	MHz
Supply Current	I <sub>DD(1)</sub>	All Outputs High	_	100	300	_	200	500	μΑ
	I <sub>DD(0)</sub>	All Outputs Low	_	100	300	_	200	500	μΑ
	I <sub>BB(1)</sub>	Outputs High, No Load	_	0.7	2.0	_	0.7	2.0	mA
	I <sub>BB(0)</sub>	Outputs Low	_	10	100	_	10	100	μΑ
Blanking to Output Delay	t <sub>PHL</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	-	2000	_	_	1000	_	ns
	t <sub>PLH</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	-	1000	_	_	850	_	ns
Output Fall Time	t <sub>f</sub>	C <sub>L</sub> = 30 pF, 90% to 10%		1450	_	_	650	_	ns
Output Rise Time	t <sub>r</sub>	C <sub>L</sub> = 30 pF, 10% to 90%	_	650	_	_	700	_	ns

Negative current is defined as coming out of (sourcing) the specified device pin.

<sup>\*</sup> Operation at a clock frequency greater than the specified minimum value is possible but not warranteed.



Dwg. No. A-12,649A

#### TIMING REQUIREMENTS

 $(T_A = +25^{\circ}C, V_{DD} = 5 \text{ V}, \text{ Logic Levels are } V_{DD} \text{ and Ground})$ 

Timing is representative of a 3.3 MHz clock. Higher speeds may be attainable with increased supply voltage; operation at high temperatures will reduce the specified maximum clock frequency.

Serial Data present at the input is transferred to the shift register on the logic "0" to logic "1" transition of the CLOCK input pulse. On succeeding CLOCK pulses, the registers shift data information towards the SERIAL DATA OUT-PUT. The SERIAL DATA must appear at the input prior to the rising edge of the CLOCK input waveform.

Information present at any register is transferred to the respective latch when the STROBE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the STROBE is held high. Applications where the latches are bypassed (STROBE tied high) will require that the BLANKING input be high during serial data entry.

When the BLANKING input is high, the output source drivers are disabled (OFF); the DMOS sink drivers are ON. The information stored in the latches is not affected by the BLANKING input. With the BLANKING input low, the outputs are controlled by the state of their respective latches.

#### TRUTH TABLE

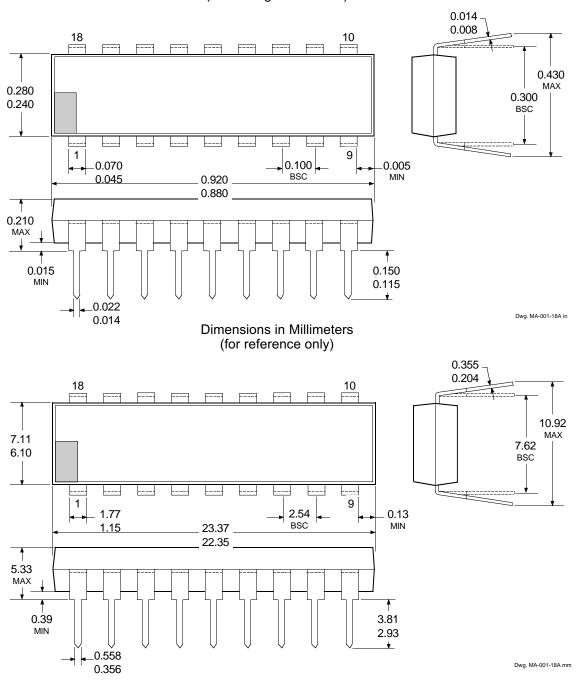
Serial		l	hift	Regi	ister	Cont	ents	Serial			Lat	ch (	Cont	ents		Output Contents								
Data Input		l	l <sub>2</sub>	I <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Data Output	Strobe Input	I <sub>1</sub>	l <sub>2</sub>	l <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Blanking	I <sub>1</sub>	l <sub>2</sub>	2 l3	,	I	N-1	I <sub>N</sub>	
Н	7	Н	R <sub>1</sub>	R <sub>2</sub>		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>																
L	7	L	R <sub>1</sub>	R <sub>2</sub>		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>																
Х	닏	$R_1$	R <sub>2</sub>	$R_3$		R <sub>N-1</sub>	R <sub>N</sub>	R <sub>N</sub>																
		Х	Χ	Χ		Χ	Χ	Х	L	R <sub>1</sub>	$R_2$	$R_3$		R <sub>N-1</sub>	$R_N$									
		P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	P <sub>N</sub>	P <sub>N</sub>	Н	P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	PN	L	P <sub>1</sub>	Р	<sub>2</sub> P	'з	F	N-1	P <sub>N</sub>	
										Х	Х	Х		Х	Χ	Н	L	L	L		L	_	L	

 $L = Low\ Logic\ Level \quad H = High\ Logic\ Level \quad X = Irrelevant \quad P = Present\ State \quad R = Previous\ State$ 



#### **UCN5810AF**

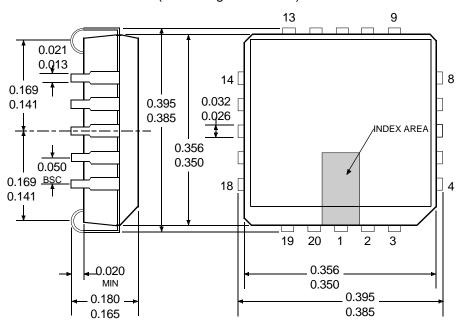
Dimensions in Inches (controlling dimensions)



- NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.
  - 2. Lead spacing tolerance is non-cumulative.
  - 3. Lead thickness is measured at seating plane or below.
  - 4. Supplied in standard sticks/tubes of 21 devices.

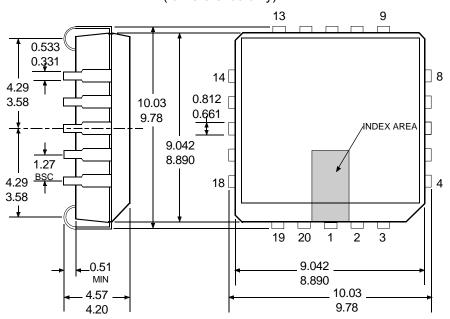
#### UCN5810EPF

Dimensions in Inches (controlling dimensions)



Dwg. MA-005-20A in

## Dimensions in Millimeters (for reference only)



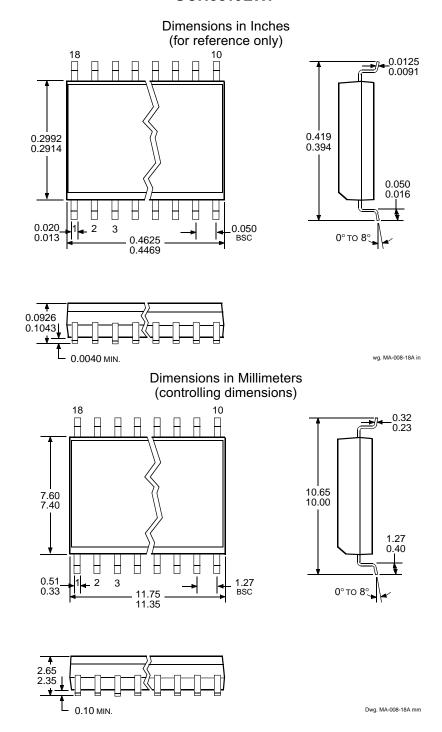
NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.

Dwg. MA-005-20A mm

- 2. Lead spacing tolerance is non-cumulative.
- 3. Supplied in standard sticks/tubes of 48 devices or add "TR" to part number for tape and reel.



#### UCN5810LWF



- NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.
  - 2. Lead spacing tolerance is non-cumulative.
  - 3. Supplied in standard sticks/tubes of 41 devices or add "TR" to part number for tape and reel.

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